

Appl. No. 09/665,034
Amdt. Dated 12/16/2004
Reply to Notice of Allowance mailed 10/06/2004

IN THE CLAIMS

Please cancel claims 17, 41, and 54 without prejudice.

The following listing of claims replaces all prior versions, and listings, of claims in the application:

- 1-13. (Cancelled).
14. (Previously Presented) The method as recited in claim 15, wherein
the conductive strip is formed by plating a conductive material onto the inner side surface of the bond shelf.
15. (Previously Presented) A method for assembling an electronic package, comprising:
forming a housing which has a bond pad located on a top surface of a bond shelf, the bond shelf having an inner side surface along a thickness of the bond shelf;
forming a conductive strip lengthwise along the inner side surface of the bond shelf; and
removing a portion of the conductive strip along the inner side surface of the bond shelf to form a pair of separate conductive strips lengthwise along the inner side surface of the bond shelf, the portion of the conductive strip is removed by drilling a portion of the inner side surface of the bond shelf including the conductive strip.
16. (Previously Presented) The method as recited in claim 15, further comprising:
mounting an integrated circuit to the housing and connecting the integrated circuit to the

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bond pad.

17. (Cancelled)

18. (Previously Presented) The method as recited in claim 15, wherein
the conductive strip is formed along the inner side surface of the bond shelf by
masking surfaces of the bond shelf except for portions of the bond shelf to be
plated, the inner side surface of the bond shelf being unmasked, and
plating a conductive material onto the inner side surface of the bond shelf.

19. (Previously Presented) The method as recited in claim 18, wherein
the conductive material is copper, and
the conductive strip is further formed by plating gold onto the copper.

20. (Previously Presented) A method for assembling an electronic package, comprising:
forming a housing which has a bond pad located on a top surface of a bond shelf, the
bond shelf having an inner side surface along a thickness of the bond shelf;
forming a conductive strip lengthwise along the inner side surface of the bond shelf; and
removing a portion of the conductive strip along the inner side surface of the bond shelf
to form a pair of separate conductive strips lengthwise along the inner side surface of the bond
shelf, the portion of the conductive strip is removed by drilling a portion of the bond shelf.

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21-34. (Cancelled)

35. (Previously Presented) The method as recited in claim 15, wherein
the forming of the conductive strip further includes

forming a portion of the conductive strip around onto the top surface of the bond
shelf to couple to the bond pad on the top surface of the bond shelf.

36. (Previously Presented) The method as recited in claim 35, wherein

the portion of the conductive strip around on the top surface of the bond shelf to
further anchor the conductive strip to the housing.

37. (Previously Presented) The method as recited in claim 15, wherein
the forming of the conductive strip further includes

forming a portion of the conductive strip around onto the top surface of the bond
shelf to form another bond pad on the top surface of the bond shelf.

38. (Previously Presented) The method as recited in claim 37, wherein

the portion of the conductive strip around on the top surface of the bond shelf to
further anchor the conductive strip to the housing.

39. (Cancelled).

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40. (Previously Presented) A method of for assembling an electronic package, comprising:
forming a housing which has a bond pad located on a top surface of a bond shelf, the bond shelf having an inside surface along an edge of the bond shelf;
plating a conductive material along the inside surface of the bond shelf; and
removing a portion of the conductive material along the inside surface of the bond shelf to form a pair of separate conductive strips along the inside surface of the bond shelf, the portion of the conductive material is removed by drilling into the edge of the bond shelf including the conductive material and the inside surface.
41. (Cancelled)
42. (Previously Presented) The method of claim 40, wherein,
the plating of the conductive material onto the inside surface of the bond shelf includes
masking surfaces of the housing that are not to be plated and
leaving surfaces of the housing unmasked that are to be plated, including the inside surface of the bond shelf that is to be plated.
43. (Previously Presented) The method of claim 42, wherein
the plating of the conductive material further includes
plating copper onto the unmasked surfaces of the housing, and
plating gold onto the copper.

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44. (Previously Presented) The method of claim 43, wherein
the portion of the conductive material is removed by
drilling into the edge of the bond shelf including the conductive material and the
inside surface.
45. (Previously Presented) The method of claim 40, wherein
the plating of the conductive material further includes
plating a portion of the conductive material from the inside surface around onto
the top surface of the bond shelf to couple to the bond pad on the top surface of the bond
shelf.
46. (Previously Presented) The method of claim 45, wherein
the portion of the conductive material plated around onto the inside surface of the
bond shelf to further anchor the conductive material to the housing.
47. (Previously Presented) The method of claim 40, wherein
the plating of the conductive material further includes
plating a portion of the conductive material from the inside surface around onto
the top surface of the bond shelf to form another bond pad on the top surface of the bond
shelf.
48. (Previously Presented) The method of claim 47, wherein

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the portion of the conductive material plated around onto the top surface of the bond shelf to further anchor the conductive material to the housing.

49. (Previously Presented) The method of claim 40, further comprising:
mounting an integrated circuit to the housing and connecting the integrated circuit to the bond pad.

50. (Cancelled).

51. (Previously Presented) The method as recited in claim 52, wherein
the conductive strip is formed by plating a conductive material onto the rectangular cavity wall of the bond shelf.

52. (Previously Presented) A method for assembling an electronic package, comprising:
forming a housing which has a plurality of bond pads located on a top surface of a bond shelf, the bond shelf forming a rectangular cavity wall along an inner side of the bond shelf;
forming a conductive strip lengthwise along the rectangular cavity wall of the bond shelf;
and

removing portions of the conductive strip along the rectangular cavity wall of the bond shelf to form a plurality of separate conductive strips along the rectangular cavity wall of the bond shelf, portions of the conductive strip are removed by drilling a portion of the rectangular cavity wall of the bond shelf including the conductive strip.

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53. (Previously Presented) The method as recited in claim 52, further comprising:
mounting an integrated circuit to the housing and connecting the integrated circuit to at
least one of the plurality of bond pads.

54. (Cancelled)

55. (Previously Presented) The method as recited in claim 52, wherein
the conductive strip is formed along the rectangular cavity wall of the bond shelf by
masking surfaces of the bond shelf except for portions of the bond shelf to be
plated, the rectangular cavity wall of the bond shelf being unmasked, and
plating a conductive material onto the rectangular cavity wall of the bond shelf.